



Advances in Hybrid Micromanufacturing Technology

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Deadline for manuscript
submissions:

closed (30 June 2022)

Message from the Guest Editors

The demand for miniaturized products and devices is increasing in our “smaller, lighter, faster, and cheaper” world. Micromanufacturing, as the bridge between macromanufacturing and nanomanufacturing, enables the manufacture of these devices in a volume production scale. Hybrid processes based on the simultaneous and controlled interaction of process mechanisms and/or energy sources/tools have been proven to positively affect micromanufacturing characteristics such as manufacturability, accuracy, surface integrity, and complexity. Hybrid micromanufacturing processes, including assisted hybrid processes, combined hybrid processes, and the controlled application of process mechanisms, can either shorten the existing process chains or realize extraordinary process performance, and hence become increasingly popular to achieve the “1+1=3” effect.

Recent years have seen the rapid application of hybrid manufacturing in aerospace, electronics, medical devices, and energy sectors. The development of hybrid micromanufacturing is still driven by industrial needs, along with the developments of new materials, energy sources, and digital approaches.





Editor-in-Chief

Message from the Editor-in-Chief

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